

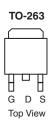
N-Channel 100-V (D-S) MOSFET

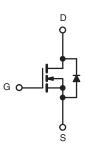
PRODUCT SUMMARY					
V _{DS} (V)	$R_{DS(on)}(\Omega)$	I _D (A)			
100	0.010 at V _{GS} = 10 V	100			
	0.023 at V _{GS} = 4.5 V	85			

FEATURES

- TrenchFET® Power MOSFET
- 175 °C Maximum Junction Temperature
- Compliant to RoHS Directive 2002/95/EC







N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS T _A = 25 °C, unless otherwise noted					
Parameter	Symbol	Limit	Unit		
Drain-Source Voltage		V_{DS}	100	V	
Gate-Source Voltage		V_{GS}	± 20	V	
Continuous Drain Current (T _J = 150 °C)	T _C = 25 °C	. I _D	100	A	
	T _C = 125 °C		75 ^a		
Pulsed Drain Current	I _{DM}	300	A		
Avalanche Current	L = 0.1 mH	I _{AS}	75		
Single Pulse Avalanche Energy ^b	L = 0.1 IIII1	E _{AS}	280	mJ	
Maximum Power Dissipation ^b	T _C = 25 °C (TO-220AB and TO-263)	P _D	250 ^c	W	
	T _A = 25 °C (TO-263) ^d	ט י	3.75		
Operating Junction and Storage Temperate	T _J , T _{stg}	- 55 to 175	°C		

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Limit	Unit		
Junction-to-Ambient	PCB Mount (TO-263) ^d	R _{thJA}	40	°C/W		
Junction-to-Ambient	Free Air (TO-220AB)	' 'thJA	62.5			
Junction-to-Case		R _{thJC}	0.6			

Notes

- a. Pulse test; pulse width \leq 300 μ s, duty cycle \leq 2 %.
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

服务热线:400-655-8788

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Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage V _{DS}		$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	100			V	
Gate-Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = 250 \mu A$	2		4	V	
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
		V _{DS} = 100 V, V _{GS} = 0 V			1		
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 100 V, V _{GS} = 0 V, T _J = 125 °C			50	μΑ	
		V _{DS} = 100 V, V _{GS} = 0 V, T _J = 175 °C			250		
On-State Drain Current ^a	I _{D(on)}	$V_{DS} = \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	120			Α	
		V _{GS} = 10 V, I _D = 30 A		0.010			
D	D	V _{GS} = 4.5 V, I _D = 20 A		0.023		Ω	
Drain-Source On-State Resistance ^a	H _{DS(on)}	V _{GS} = 10 V, I _D = 30 A, T _J = 125 °C		0.020			
		V _{GS} = 10 V, I _D = 30 A, T _J = 175 °C		0.030			
Forward Transconductance ^a	9 _{fs}	$V_{DS} = 15 \text{ V}, I_{D} = 30 \text{ A}$	25			S	
Dynamic ^b							
Input Capacitance	C _{iss}			6550		pF	
Output Capacitance	C _{oss}	$V_{GS} = 0 \text{ V}, V_{DS} = 25 \text{ V}, f = 1 \text{ MHz}$		665			
Reverse Transfer Capacitance	C _{rss}]		265			
Total Gate Charge ^c	Q_g			105	160		
Gate-Source Charge ^c	Q_gs	$V_{DS} = 50 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 85 \text{ A}$		17		nC	
Gate-Drain Charge ^c	Q_{gd}	7		23			
Turn-On Delay Time ^c	t _{d(on)}			12	25		
Rise Time ^c	t _r	$V_{DD} = 50 \text{ V}, R_{L} = 0.6 \Omega$		90	135		
Turn-Off DelayTime ^c	t _{d(off)}	$I_D \cong 85 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 2.5 \Omega$		55	85	ns	
Fall Time ^c	t _f	7		130	195		
Source-Drain Diode Ratings and Cha	racteristics T _C	= 25 °C ^b					
Continuous Current	I _S				85	^	
Pulsed Current	I _{SM}				240	Α	
Forward Voltage ^a	V _{SD}	I _F = 85 A, V _{GS} = 0 V		1.0	1.5	V	
Reverse Recovery Time	t _{rr}			85	140	ns	
Peak Reverse Recovery Current	I _{RM(REC)}	I _F = 50 A, dI/dt = 100 A/μs		4.5	7	Α	
Reverse Recovery Charge	Q _{rr}	1		0.17	0.35	μC	

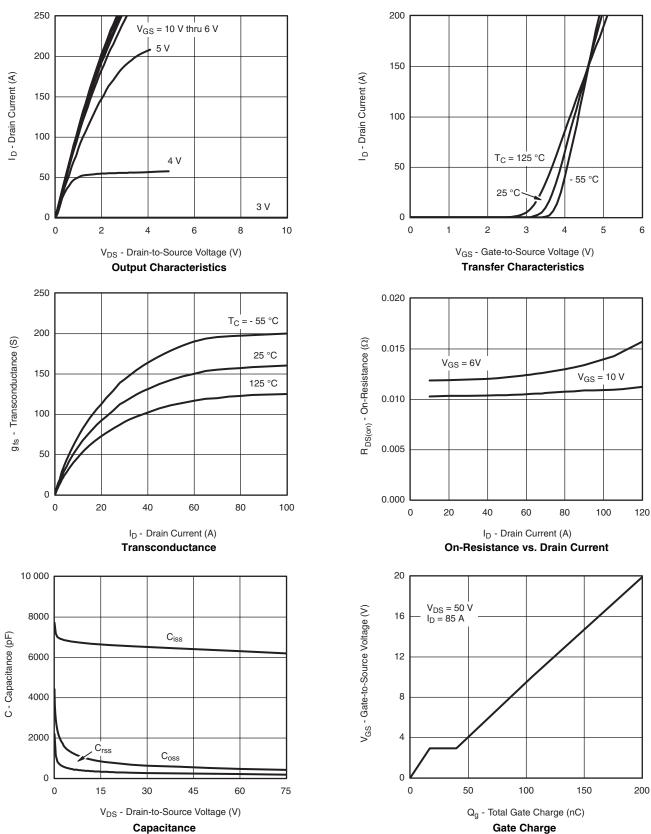
Notes:

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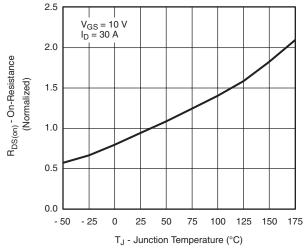


TYPICAL CHARACTERISTICS $T_A = 25$ °C, unless otherwise noted

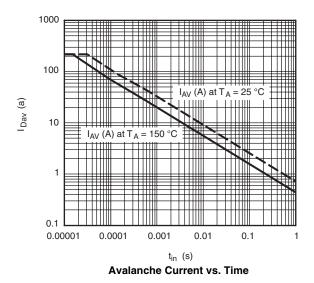




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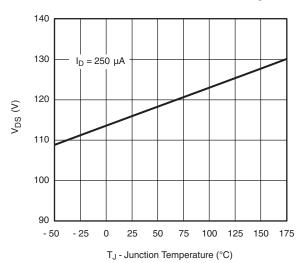


On-Resistance vs. Junction Temperature



T_J = 150 °C T_J = 25 °C T_J

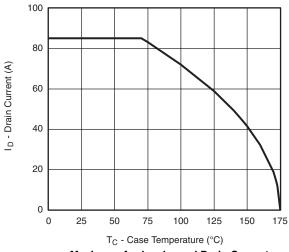
Source-Drain Diode Forward Voltage

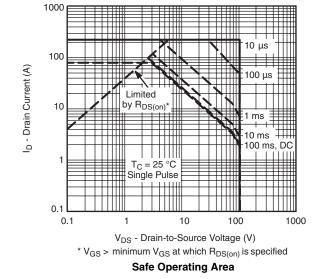


T_J - Drain-Source Breakdown vs. Junction-Temperature

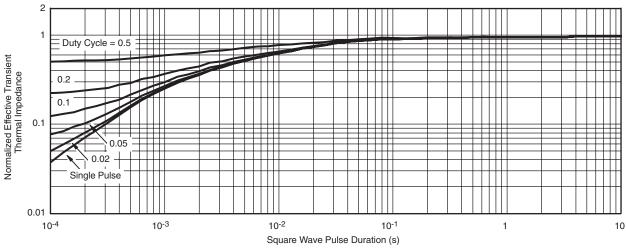


THERMAL RATINGS





Maximum Avalanche and Drain Current vs. Case Temperature

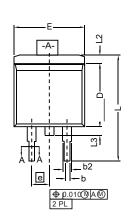


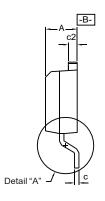
Normalized Thermal Transient Impedance, Junction-to-Case

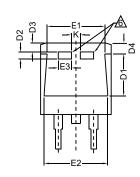
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TO-263 (D²PAK): 3-LEAD

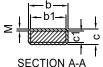








DETAIL A (ROTATED 90°)



_	Ţ	— b — b1	-	ļ	ţ
_	\prod			c1	ပ
	SE	CTIC	N.	† A-A	t

- 1. Plane B includes maximum features of heat sink tab and plastic.
- 2. No more than 25 % of L1 can fall above seating plane by max.
- 3. Pin-to-pin coplanarity max. 4 mils.
- 4. *: Thin lead is for SUB, SYB. Thick lead is for SUM, SYM, SQM.
- 5. Use inches as the primary measurement.

 This feature is for thick lead.

		INC	HES	MILLIMETERS		
	DIM.	MIN.	MAX.	MIN.	MAX.	
A		0.160	0.190	4.064	4.826	
	b	0.020	0.039	0.508	0.990	
	b1	0.020	0.035	0.508	0.889	
	b2	0.045	0.055	1.143	1.397	
c*	Thin lead	0.013	0.018	0.330	0.457	
"	Thick lead	0.023	0.028	0.584	0.711	
c1	Thin lead	0.013	0.017	0.330	0.431	
"	Thick lead	0.023	0.027	0.584	0.685	
	c2	0.045	0.055	1.143	1.397	
	D	0.340	0.380	8.636	9.652	
	D1	0.220	0.240	5.588	6.096	
	D2	0.038	0.042	0.965	1.067	
	D3	0.045	0.055	1.143	1.397	
	D4	0.044	0.052	1.118	1.321	
	E	0.380	0.410	9.652	10.414	
	E1	0.245	-	6.223	-	
	E2	0.355	0.375	9.017	9.525	
	E3	0.072	0.078	1.829	1.981	
	е	0.100 BSC		2.54 BSC		
	K	0.045	0.055	1.143	1.397	
	L 0.57		0.625	14.605	15.875	
	L1	0.090	0.110	2.286	2.794	
	L2	0.040	0.055	1.016	1.397	
	L3	0.050	0.070	1.270	1.778	
	L4	0.010 BSC		0.254 BSC		
	М	-	0.002	-	0.050	
FCN: T13-0707-Rev. K. 30-Sen-13						

ECN: T13-0707-Rev. K, 30-Sep-13

DWG: 5843



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DMN2080UCB4-7 DMN61D9UWQ-13 US6M2GTR DMN31D5UDJ-7 DMP22D4UFO-7B DMN1006UCA6-7 DMN16M9UCA6-7
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BXP2N65D BXT1150N10J BXT1700P06M TSM60NB380CP ROG RQ7L055BGTCR DMNH15H110SK3-13 SLF10N65ABV2
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